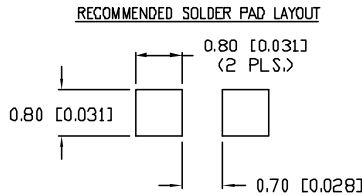
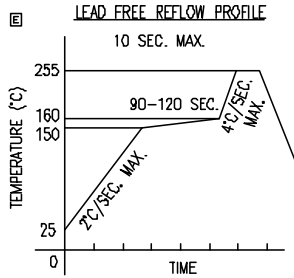
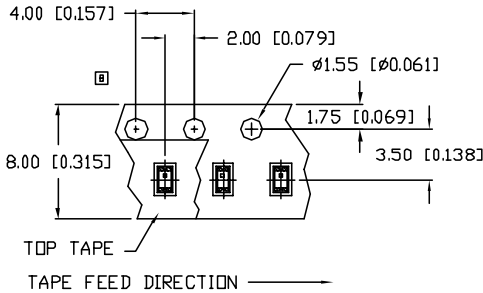
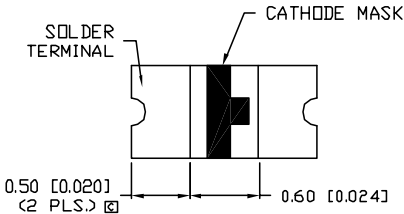
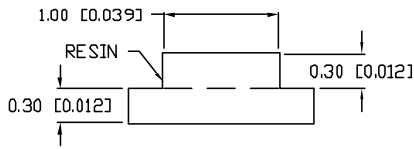
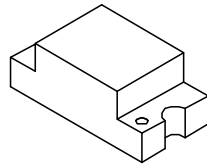
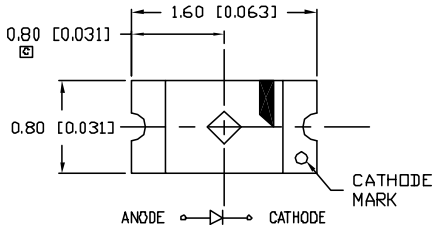


UNCONTROLLED DOCUMENT



PART NUMBER  
SML-LX0603IW-TR

REV.  
E

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10BRDR. & REDRAWN.	9.30.98
B	E.C.N. #10644.	7.18.00
C	E.C.N. #10933.	12.3.02
D	E.C.N. #10967.	3.14.03
E	E.C.N. #1114B.	12.06.04

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		635		nm	
FORWARD VOLTAGE		2.0	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		14		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	RED				
EPOXY LENS FINISH:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	100	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	50	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-25 TO +85	°C
STORAGE TEMP.	-30 TO +85	°C

\*  $t < 10\mu\text{s}$

NOTES:

- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS

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\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.038), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030), MIN=+DECIMAL PRECISION MAX=-DECIMAL PRECISION

REV. E	PART NUMBER SML-LX0603IW-TR
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1.6mm x 0.8mm PCB CHIP, SURFACE MOUNT LED,  
635nm RED LED, MILKY WHITE DIFFUSED LENS.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT	CHECKED BY:	APPROVED BY:	DATE: 7.22.97 PAGE: 1 OF 1 SCALE: N/A
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